AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. - 4. (Cancelled)

5. (Currently Amended) A manufacturing method for a liquid crystal device comprising:

attaching a first substrate and a second substrate to each other with a liquid crystal sealed in therebetween so that a projecting portion of the first substrate projects outward beyond an outer edge of the second substrate;

forming a first conductive member on a surface of ~~a peripheral portion of~~ the first substrate;

forming a second conductive member on a portion of the second substrate that opposes the first conductive member;

forming an alignment layer having a thickness of 100 to 400 angstroms to cover a surface of the projecting portion as well as a surface of ~~at least one of~~ the first conductive member and the second conductive member; ~~and~~

using compression bonding to conductively connect the first conductive member and the second conductive member in a vertical conducting portion with a conductive material containing conductive particles and non-conductive spacers, the conductive particles having an outside diameter that is 5 to 20% larger than an outside diameter of the non-conductive spacers, ~~said~~ the compression- bonding causing the

conductive particles to break through the alignment layer to conductively contact the ~~at least one of the~~ first conductive member and the second conductive member; and

~~wherein the alignment layer has a thickness of 100 to 400 angstroms and the conductive particles have an outside diameter that is 5 to 20% larger than an outside diameter of the non-conductive spacers.~~ removing the alignment layer on the surface of the projecting portion after the compression bonding.

6. (Currently Amended) The manufacturing method for a liquid crystal device according to Claim 5, wherein ~~said~~ the step for forming the alignment layer further comprises forming the alignment layer ~~on an entire area of~~ the whole surface where the first substrate and the second substrate oppose each other.

7. (Previously Presented) The manufacturing method for a liquid crystal device according to Claim 5, wherein the conductive material is used as a sealing material for sealing the liquid crystal between the first substrate and the second substrate.

8. – 11. (Cancelled)

12. (New) The manufacturing method for a liquid crystal device according to Claim 5, wherein the alignment layer on the surface of the projecting portion is removed by plasma ashing after the compression bonding.